

ABSTRACT OF THE DISCLOSURE

A method for producing printed wiring boards comprises the steps of perforating through holes at predetermined positions in an adhesive insulator sheet, filling the through holes with a conductive material such as a conductive paste or metal balls, transferring conductive wiring patterns that have been formed on surfaces of releasable supporting sheets onto the surfaces of the adhesive insulator sheet by heat and pressure. Simultaneously, interlayer via-connections are performed by means of the conductive material filled into the through holes.

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